

12500 TI Boulevard, MS 8640, Dallas, Texas 75243

PCN#20211123003.0 Marking Standardization for Select Devices Information Only

Date:December 17, 2021To:TOKYO ELECTRON DEVICE (DSTR) PCN

Dear Customer:

This is an information-only announcement of a change to a device that is currently offered by Texas Instruments.

The changes discussed within this notification are for your information only.

Any negotiated alternative change requirements will be provided via the customer's defined process. Customers with previously negotiated, special requirements will be handled separately. Any inquiries should be directed to your local Field Sales Representative.

For questions regarding this notice, contact your local Field Sales Representative or the PCN Team (<u>PCN_ww_admin_team@list.ti.com</u>).

Sincerely,

PCN Team SC Business Services

20211123003.0 Attachment: 1

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, these are the devices that you have purchased within the past twenty-four (24) months (60 months for Automotive devices). The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
LM26001QMXAX/NOPB	null
LMK00804BPWR	null
LM5160QPWPRQ1	null
LM5161PWPT	null
UCC2813QDR-5-M	null
LM26001MXAX/NOPB	null
LMK00804BPW	null
LMK00725PW	null
LMK00725PWR	null
LM3492HCQMHX/NOPB	null
TDC1000PWR	null
TPS92511DDAR	null
LM5161QPWPRQ1	null
LM5161QPWPTQ1	null
LM26001BMHX/NOPB	null

Technical details of this Product Change follow on the next page(s).

PCN Nu	mber:	r: 20211123003.0				PCN Date:		December 17, 2021	
Title: Marking Standardization for Select Devices									
Customer Contact: PCN Manager Dept:			Quality Services						
Change Type:									
Assembly Site			Assembly Process				Assembly Materials		
Desi	gn	Datashee		eet		Mechani		cal Specification	
Test	Site	Device Markir		Marking			Test Process		
Wafe	er Bump Site		Wafer Bump Material			Wafer Bump Process			
Wafe	er Fab Site			Wafer Fab Materials			Wafer Fab Process		
				Part nu	imber ch	ange			

PCN Details

Description of Change:

This notice is to communicate an update in the device symbolization format for the devices in the product affected selection as follows:

	Current	New
**ECAT	Include Value	Remove
Pin One Designator	Dot (filled)	Dot (empty)
TI Bug	Include	Replace with "TI" text
Example	AO19A6JHU LMH65 02MT	

** - Not all devices have ECAT information included in the symbolization, but for the ones that do, this information will be removed.

Reason for Change:

Marking Standardization

Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative): None

Changes to product identification resulting from this PCN:

Device symbolization

Product Affected:

See page 2 above

For questions regarding this notice, e-mails can be sent to the contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
WW PCN Team	PCN ww admin team@list.ti.com

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